

SOT513-1

plastic thermal enhanced thin quad flat package; 80 leads;
body 14 x 14 x 1 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP80
Package type industry code	HTQFP80
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
n ₂	actual quantity of termination	-	-	80	-	

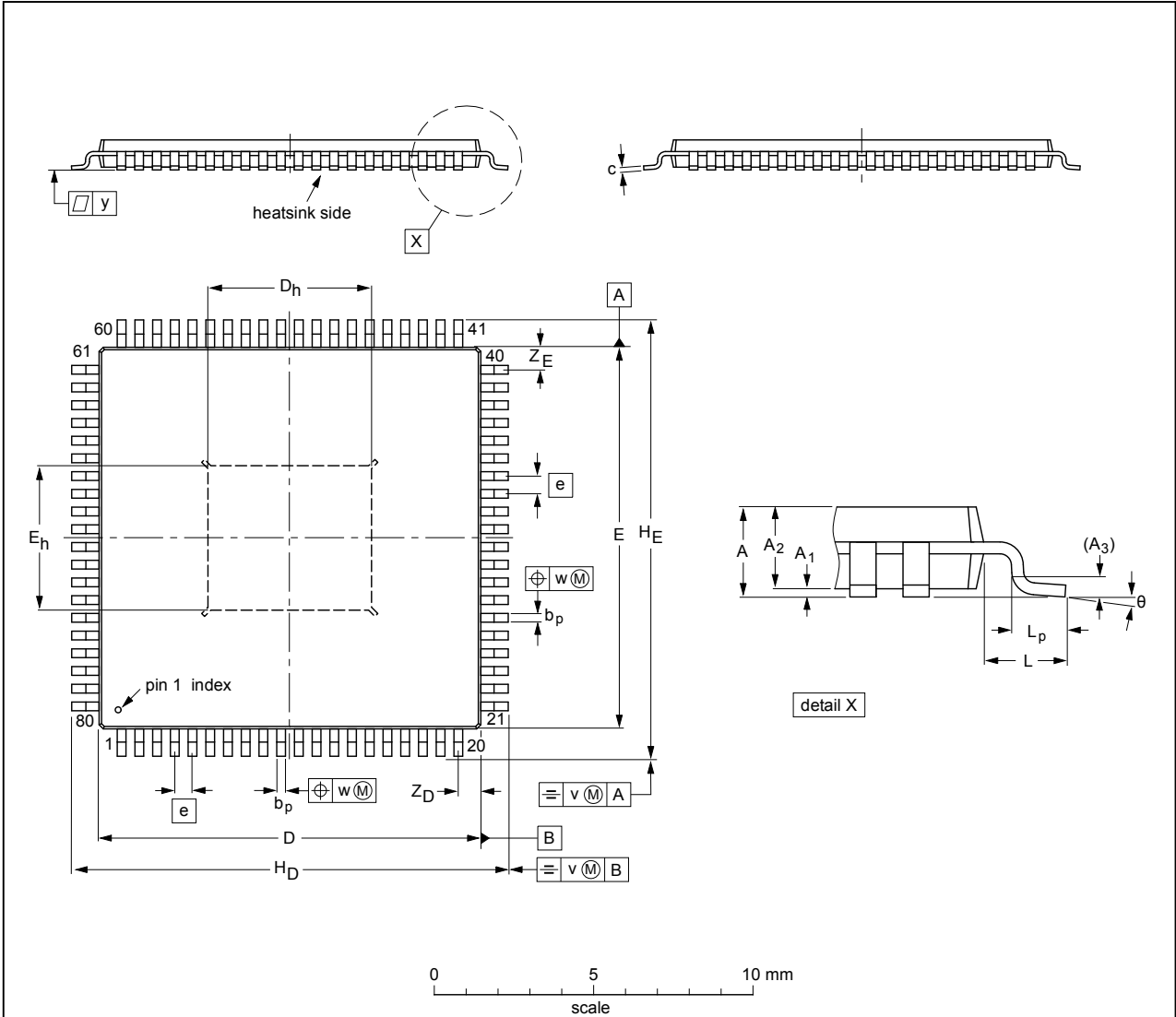


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2. Package outline

HTQFP80: plastic thermal enhanced thin quad flat package; 80 leads;
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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.2	0.15 0.05	1.05 0.95	0.25	0.38 0.22	0.20 0.09	14.1 13.9	6.5 5.5	14.1 13.9	5.8 4.8	0.65	16.15 15.85	16.15 15.85	1	0.75 0.45	0.2	0.13	0.1	1.02 0.63	1.02 0.63	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT513-1						99-11-23- 03-02-20

Fig. 1. Package outline HTQFP80 (SOT513-1)

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3. Soldering

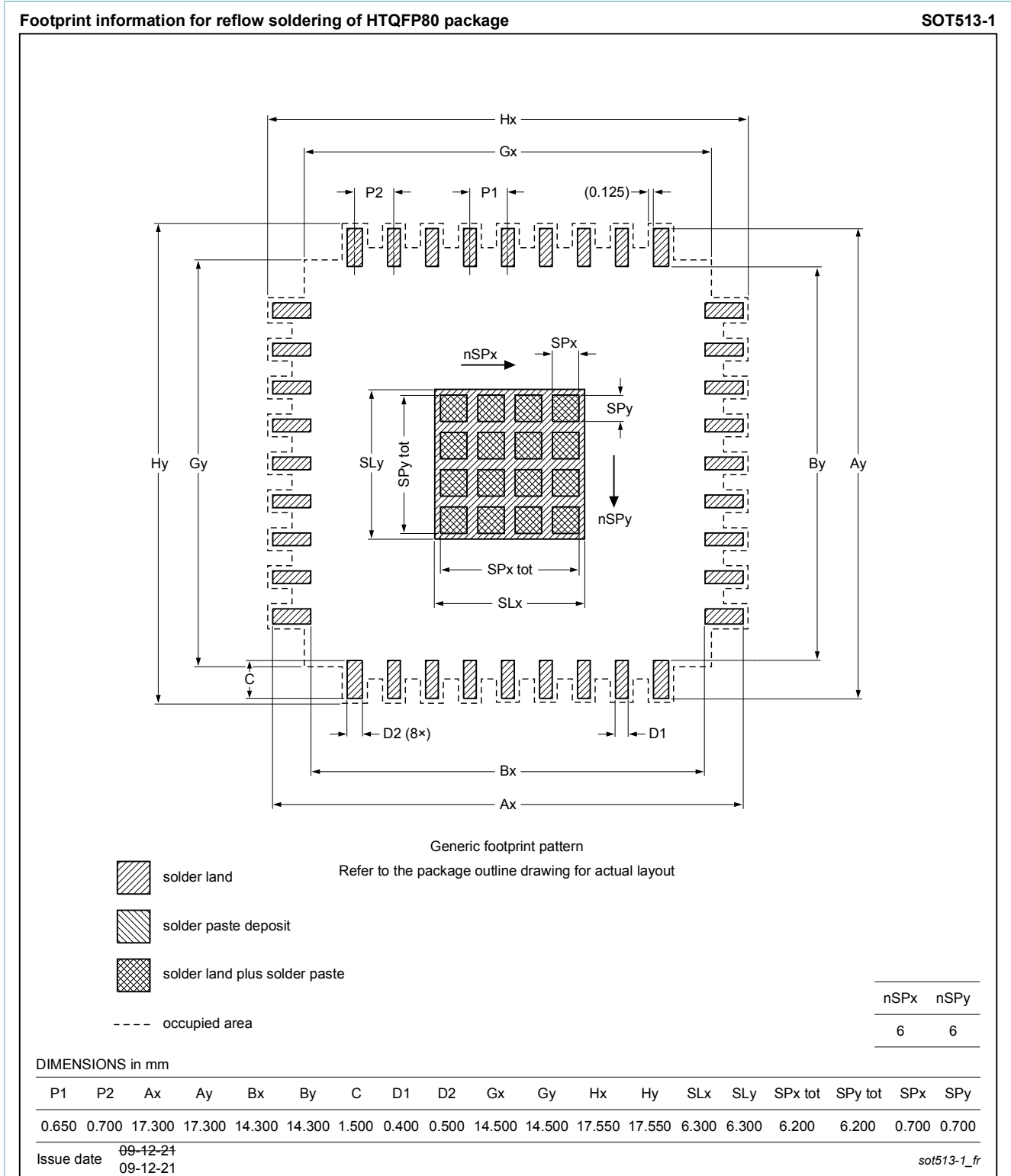


Fig. 2. Reflow soldering footprint for HTQFP80 (SOT513-1)

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4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com

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